ABSTRACT

LEADFRAME FOR DIE STACKING APPLICATIONS AND RELATED DIE STACKING CONCEPTS

A leadframe design (and method of forming the leadframe design), comprising: an inner die pad structure lying in a first plane; and an outer die pad structure supported by outer tie bars and connected to the inner die pad by inner tie bars. The outer die pad structure lying in a second plane spaced apart from the inner die pad structure first plane. An outer package surrounds at least the inner die pad structure and the inner tie bars. The outer die pad structure being supported by the outer tie bars. The outer package having outer walls. Lead fingers extend through the outer package outer walls and include respective inner portions extending into the outer package proximate the inner and outer die pad structures. The inner portions of the lead fingers lie in a third plane, wherein at least one of the inner die pad structure first plane and the outer die pad structure second plane lie outside of the lead finger inner portions third plane and wherein a first chip is affixed to the inner die pad structure and a second chip is affixed to the outer die pad structure. (Fig. 1)